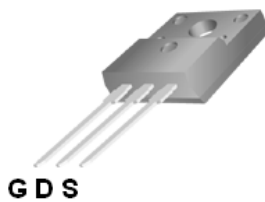


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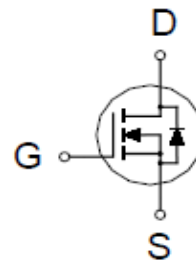
N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
600V	$1.05\Omega @ V_{GS} = 10V$	8A



TO-220F
TO-220FS



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	600	V
Gate-Source Voltage		V_{GS}	± 30	
Continuous Drain Current ²	$T_C = 25\text{ }^\circ\text{C}$	I_D	8	A
	$T_C = 100\text{ }^\circ\text{C}$		5	
Pulsed Drain Current ¹		I_{DM}	25	
Avalanche Current ³		I_{AS}	3.5	
Avalanche Energy ³		E_{AS}	61.2	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	36	W
	$T_C = 100\text{ }^\circ\text{C}$		14	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		3.4	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Ensure that the channel temperature does not exceed 150°C .

³ $V_{DD} = 50V$, $L = 10\text{mH}$, starting $T_J = 25^\circ\text{C}$

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N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	600			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	2.7	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			± 100	nA
Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V, T_C = 25\text{ }^{\circ}C$			1	μA
		$V_{DS} = 480V, V_{GS} = 0V, T_C = 100\text{ }^{\circ}C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 4A$		0.83	1.05	Ω
Forward Transconductance ¹	g_{fs}	$V_{DS} = 10V, I_D = 4A$		10.5		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		1270		pF
Output Capacitance	C_{oss}			114		
Reverse Transfer Capacitance	C_{rss}			10		
Total Gate Charge ²	Q_g	$V_{DD} = 480V, V_{GS} = 10V, I_D = 8A$		29		nC
Gate-Source Charge ²	Q_{gs}			5.1		
Gate-Drain Charge ²	Q_{gd}			8.4		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 300V, I_D = 8A,$ $R_G = 25\Omega$		23		nS
Rise Time ²	t_r			31		
Turn-Off Delay Time ²	$t_{d(off)}$			115		
Fall Time ²	t_f			50		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25\text{ }^{\circ}C$)						
Continuous Current ³	I_S				8	A
Forward Voltage ¹	V_{SD}	$I_F = 8A, V_{GS} = 0V$			1	V
Reverse Recovery Time	t_{rr}	$I_F = 8A, dI_F/dt = 100A / \mu S$		390		nS
Reverse Recovery Charge	Q_{rr}			3.9		μC

¹Pulse test : Pulse Width ≤ 380 μsec, Duty Cycle ≤ 2%.

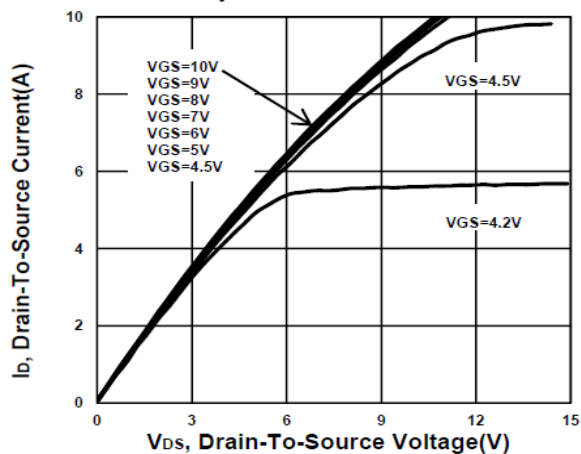
²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

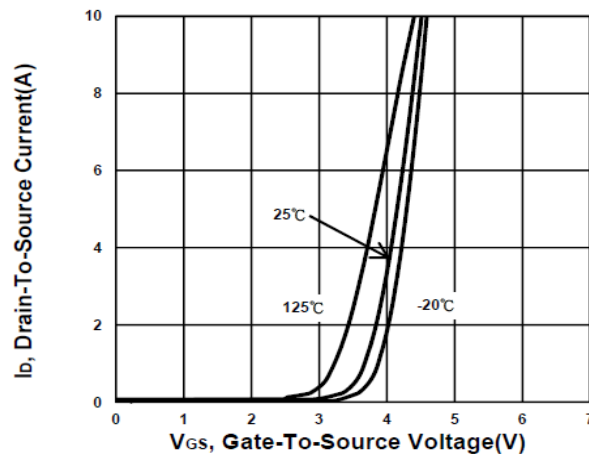
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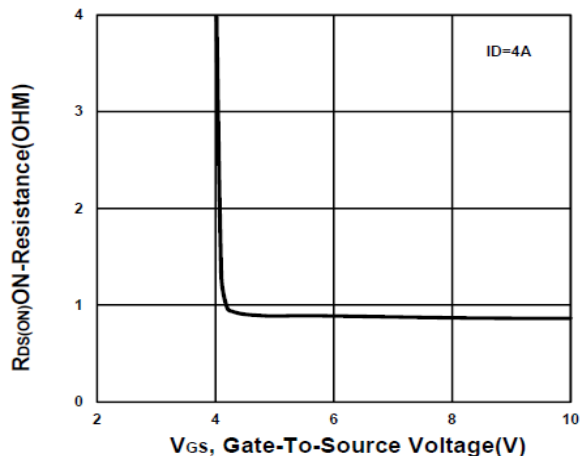
Output Characteristics



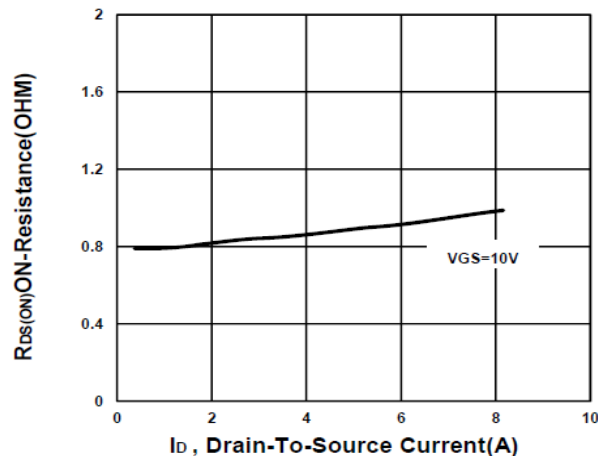
Transfer Characteristics



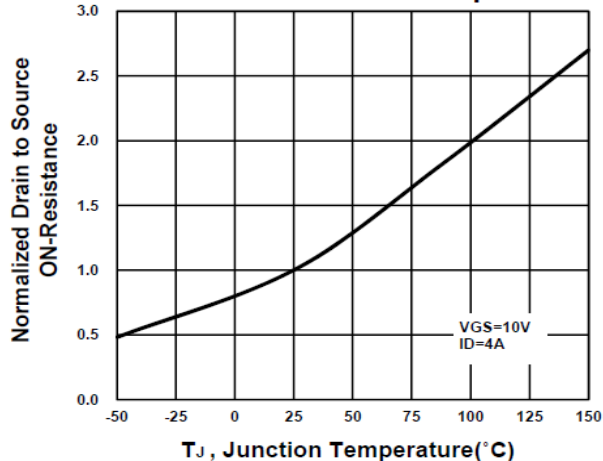
On-Resistance VS Gate-To-Source



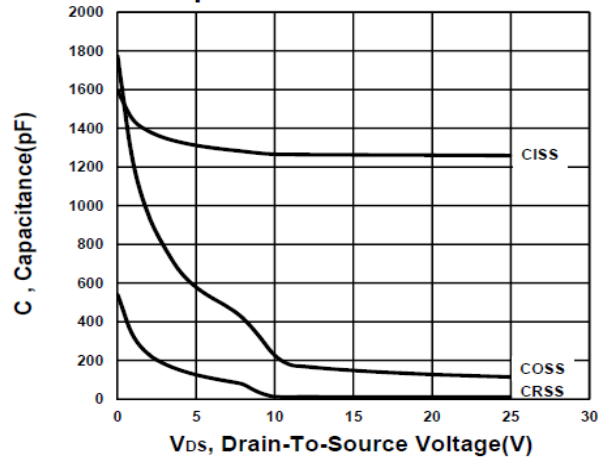
On-Resistance VS Drain Current



On-Resistance VS Temperature



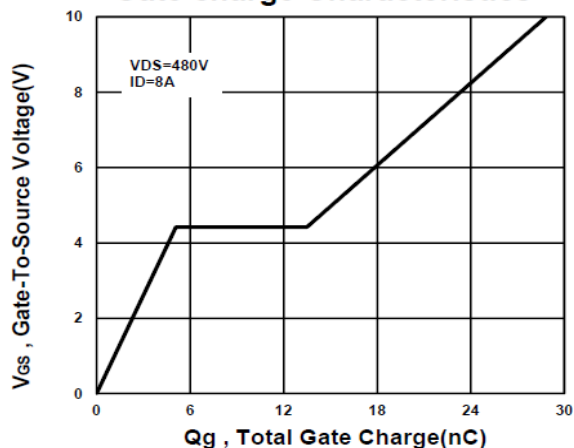
Capacitance Characteristic



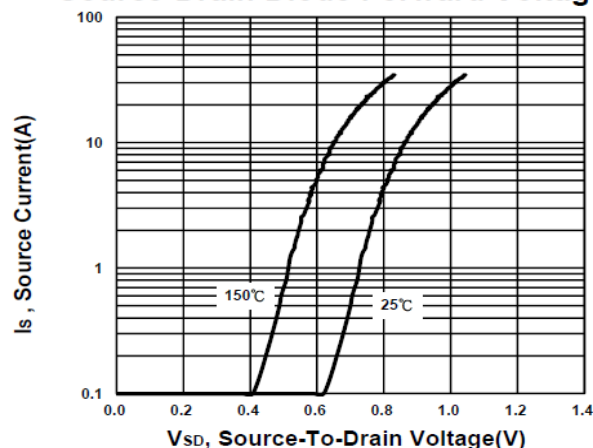
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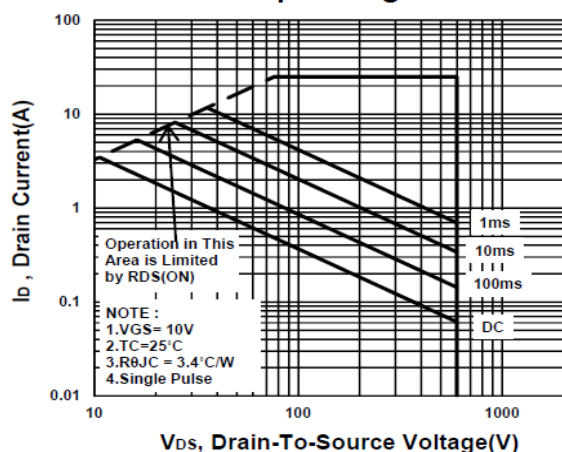
Gate charge Characteristics



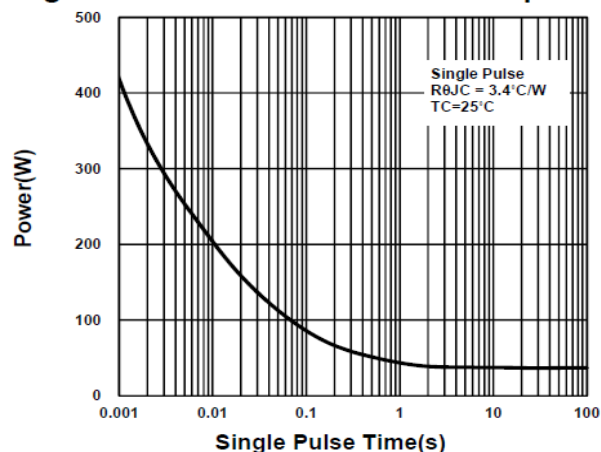
Source-Drain Diode Forward Voltage



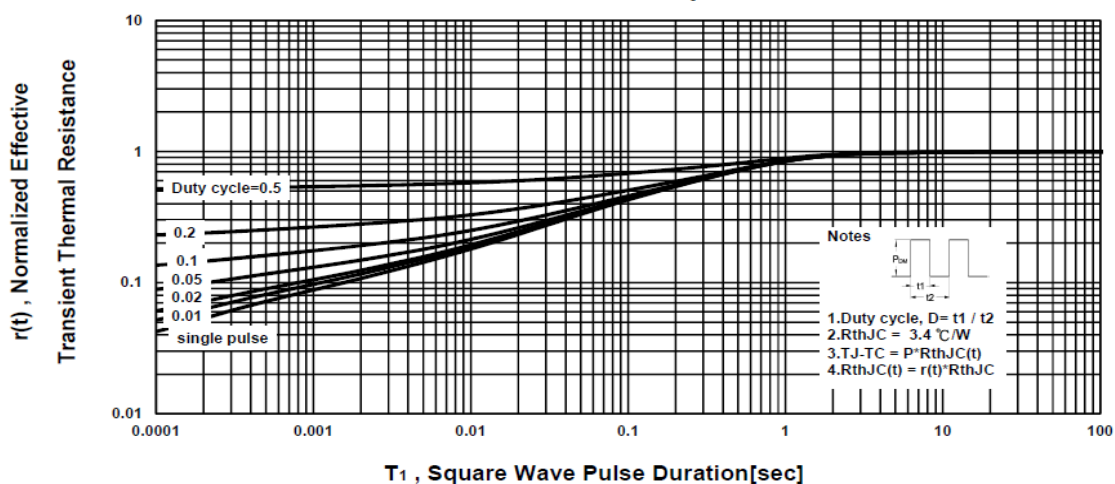
Safe Operating Area



Single Pulse Maximum Power Dissipation



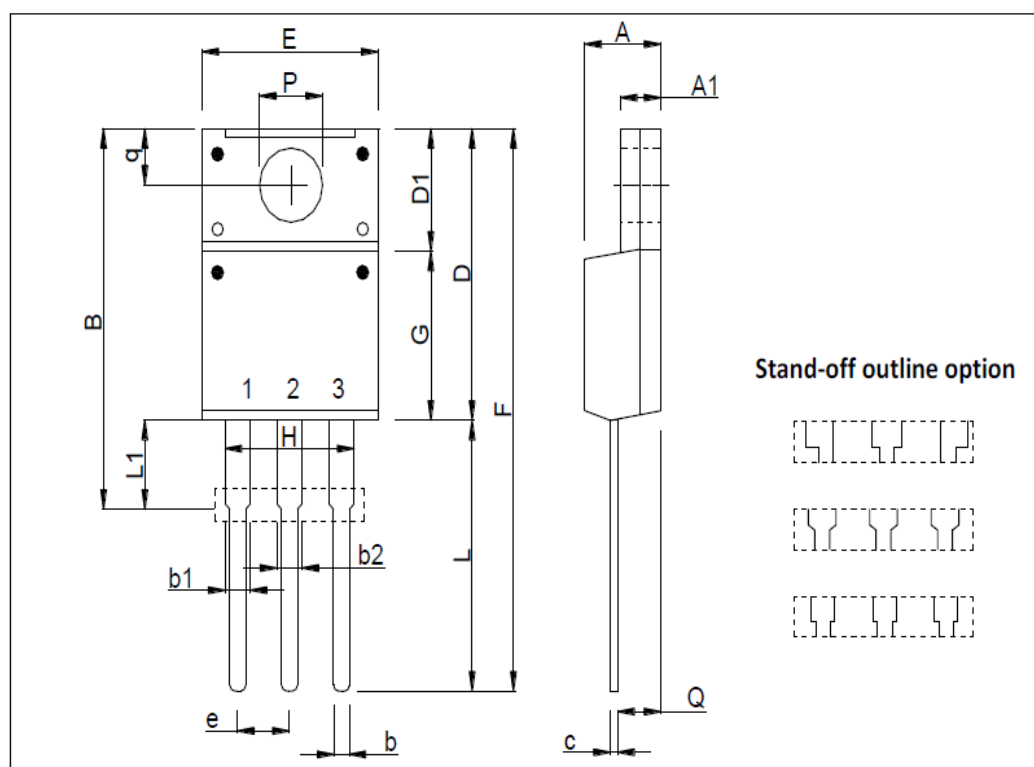
Transient Thermal Response Curve



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N-Channel Enhancement Mode MOSFET

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.4		4.93	e	2.34		2.74
A1	2.34		3.1	F	27.2		30.6
B	18.8		20	G	7.7		9.39
b	0.65		1	H	6.18		6.82
b1	0.93		1.6	L	12.7		14.2
b2	0.95		1.6	L1	2.88		3.7
c	0.4		1	P	2.98		3.7
D	13.5		16.4	Q	2.3		2.96
D1	6.48		6.95	q	3.1		3.8
E	9.8		10.4				



*因为各家封装模具不同而外观略有所差异，不影响电性及Layout。

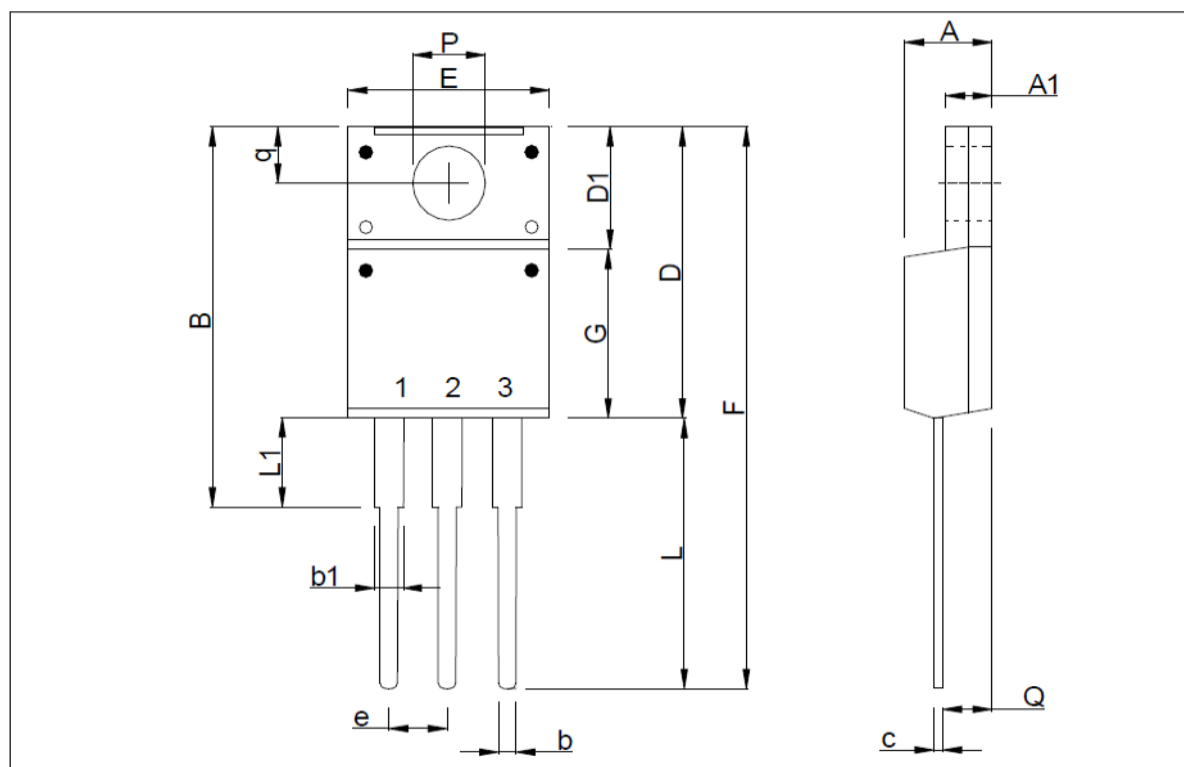
P0860ETF / P0860ETFS

N-Channel Enhancement Mode MOSFET

Package Dimension

TO-220FS (3-Lead) MECHANICAL DATA

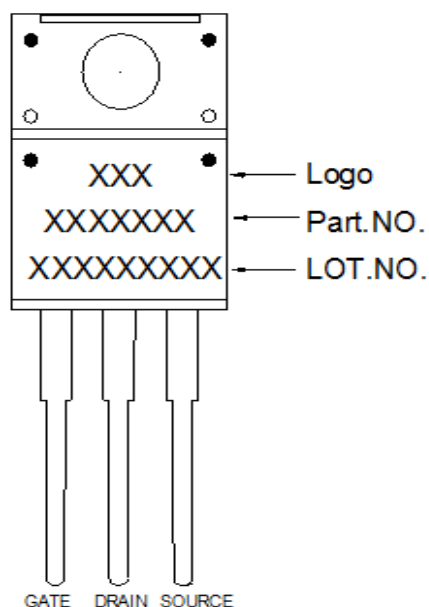
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.2	4.7	4.93	e	2.05	2.54	3.05
A1	2.34	2.8	3.1	F	28.04		30.3
B	17.7		20.3	G	8.2	8.87	9.57
b	0.65	0.8	1.05	L	12.37		14.3
b1	0.9	1.3	1.5	L1	1.4	2.3	2.5
c	0.4	0.7	1.0	P	2.98	3.2	3.4
D	15.37		16.3	Q	2.1	2.6	2.96
D1	5.5		7.5	q	3.0	3.5	3.8
E	9.7	10.16	10.36				



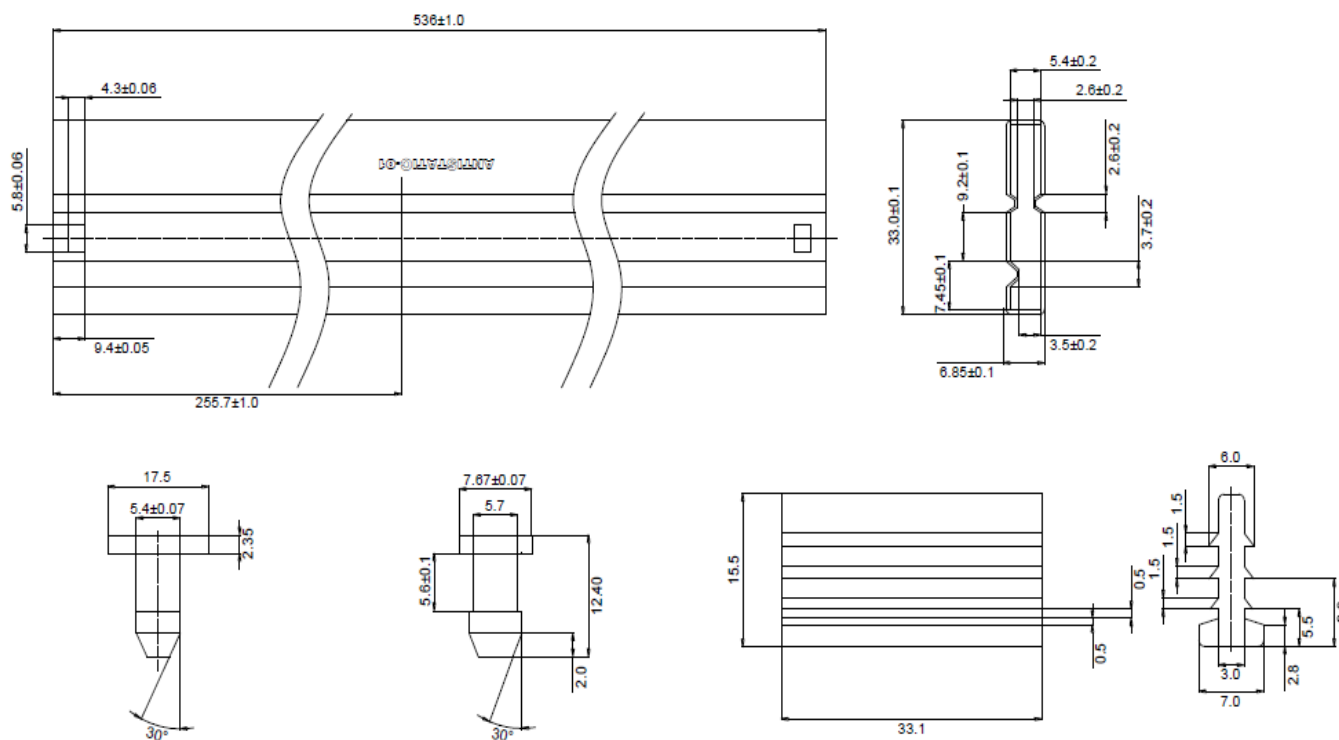
P0860ETF / P0860ETFS

N-Channel Enhancement Mode MOSFET

A. Marking Information



B. Tape&Reel Information:50pcs/Tube(2000pcs/Box)

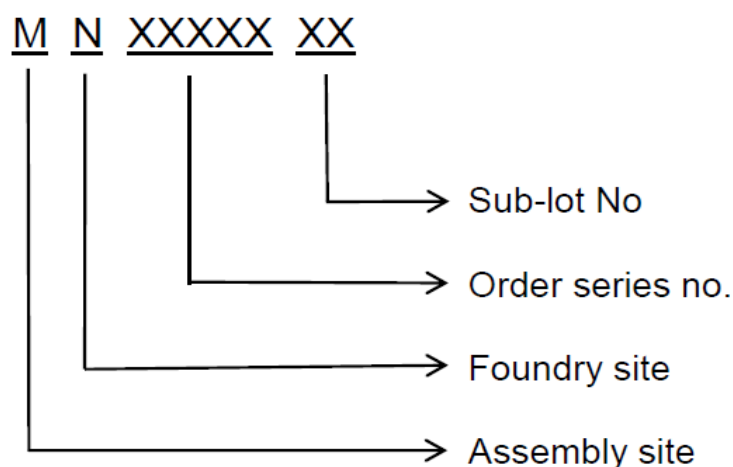


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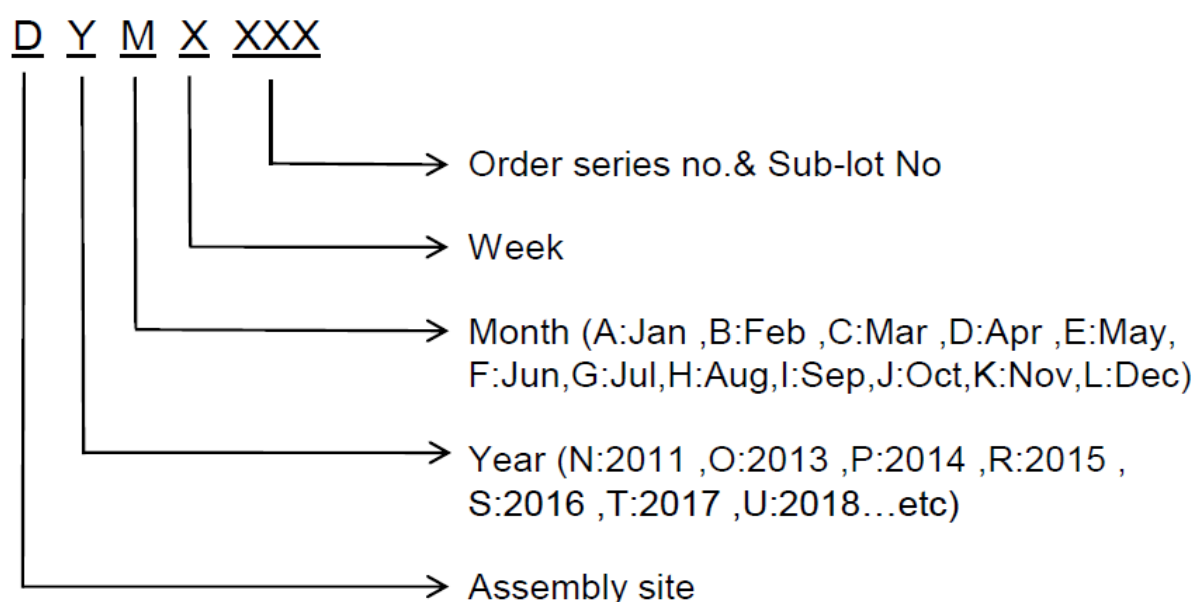
N-Channel Enhancement Mode MOSFET

C. Lot No.&Date Code rule

1.Lot No.



2.Date Code





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N-Channel Enhancement Mode MOSFET

D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G"和"Q"的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY, Insert "/" between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least